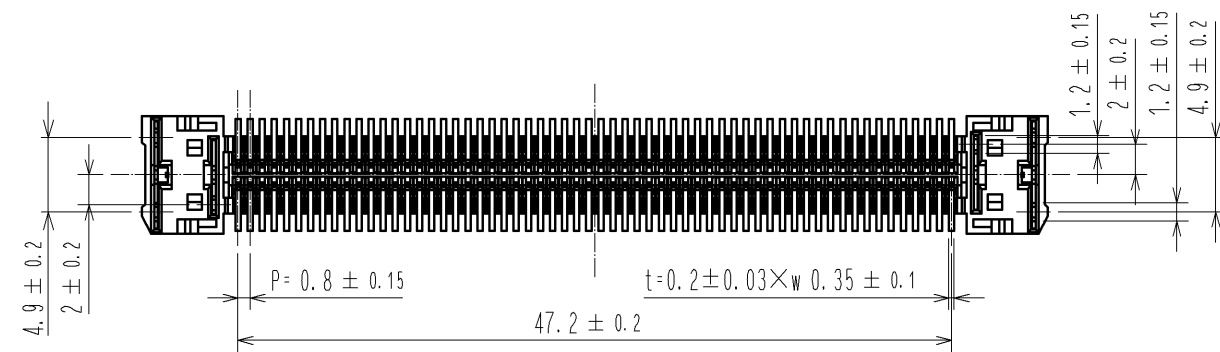
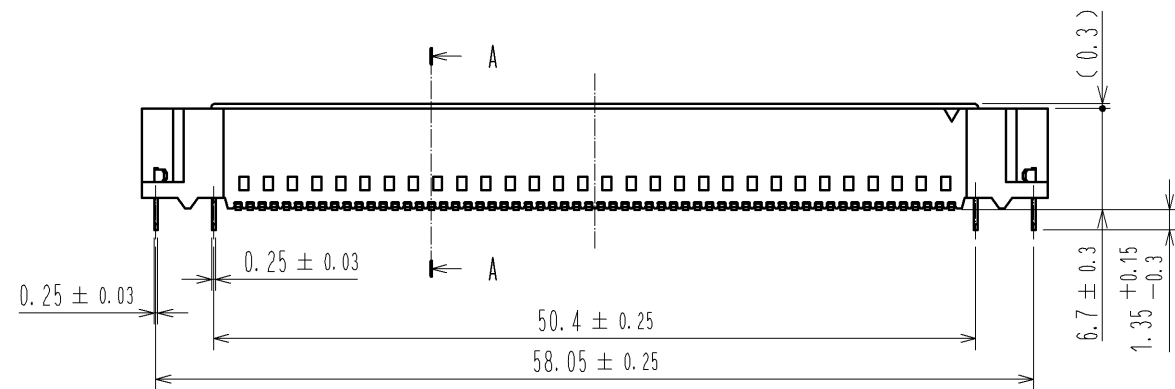
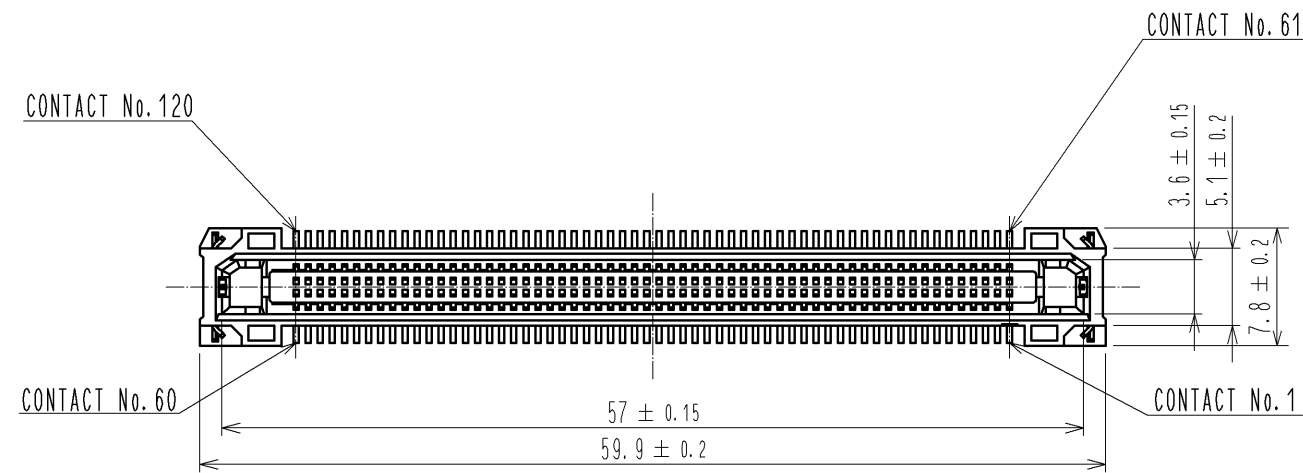


APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾		STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾
	VOLTAGE	100 V AC		STORAGE HUMIDITY RANGE	40 % TO 70 % ⁽²⁾
	CURRENT	0.5 A (SIGNAL CONTACT) ⁽³⁾ 3 A (MF CONTACT)		OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	QT AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x x
MARKING		CONFIRMED VISUALLY.			x x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.	x —
INSULATION RESISTANCE		250 V DC.		1000 MΩ MIN.	x —
VOLTAGE PROOF		300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x —
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES		MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 70 N MAX. WITHDRAWAL FORCE: 7 N MIN.	x —
MECHANICAL OPERATION		500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x —
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.	x —
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x —
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x —
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x —
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	x —
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. ⁽³⁾ THE RATED CURRENT APPLIES TO PER CONTACT. APPLY 0.4A WHEN ALL THE CONTACTS ARE USED FOR CURRENT CARRYING. Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	14. 07. 16
			CHECKED	HT. YAMAGUCHI	14. 07. 15
			DESIGNED	TH. SANO	14. 07. 15
			DRAWN	TH. SANO	14. 07. 15
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-349391-00
HRS	SPECIFICATION SHEET		PART NO.	FX18-120S-0.8SV10	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0059-2-00	△ 1/1



NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.

2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.

3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)

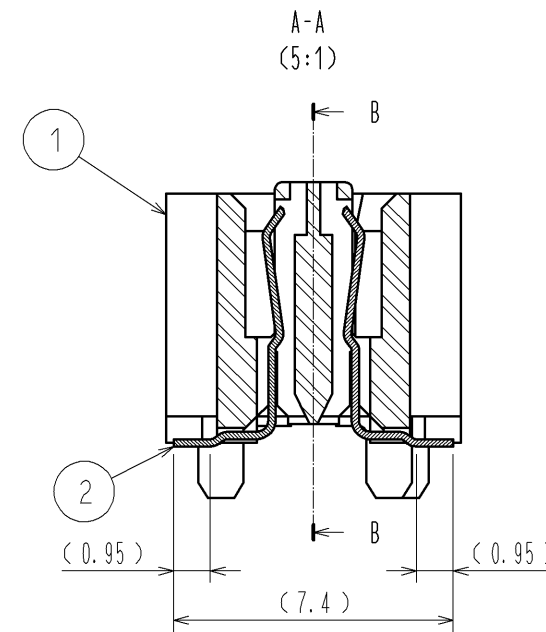
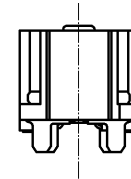
4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)

REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.

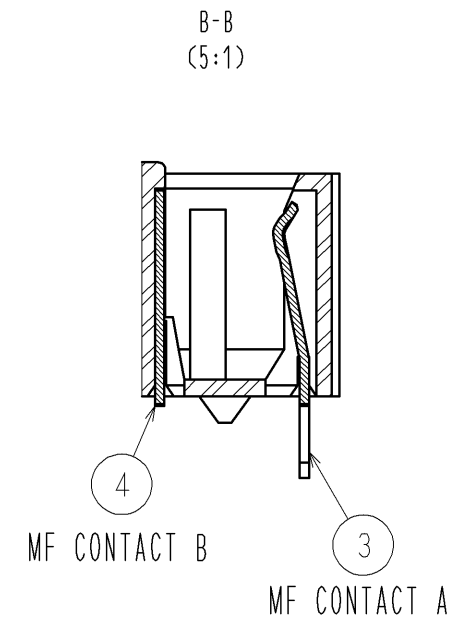
5 THIS IS PACKAGED IN TRAY. (40pcs/TRAY)

6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.

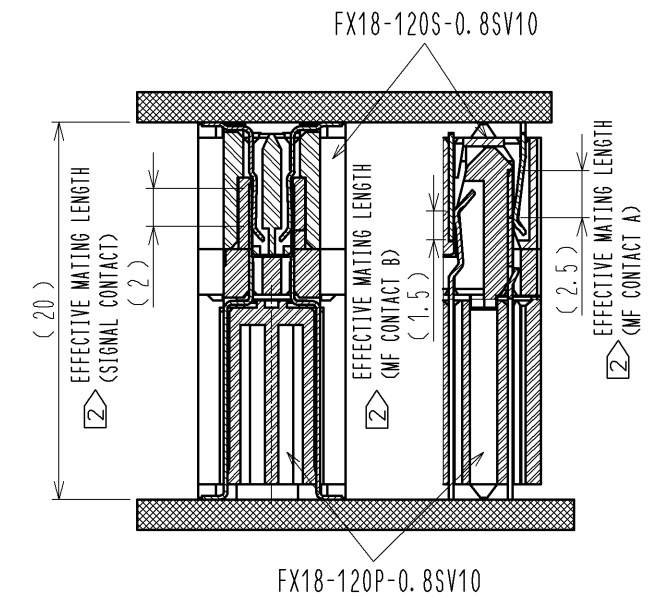
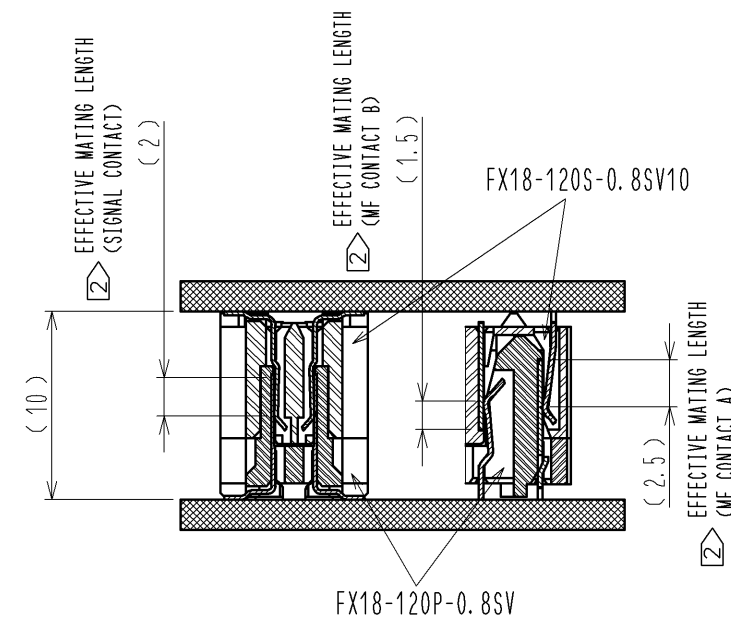
7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.



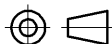



CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=10mm

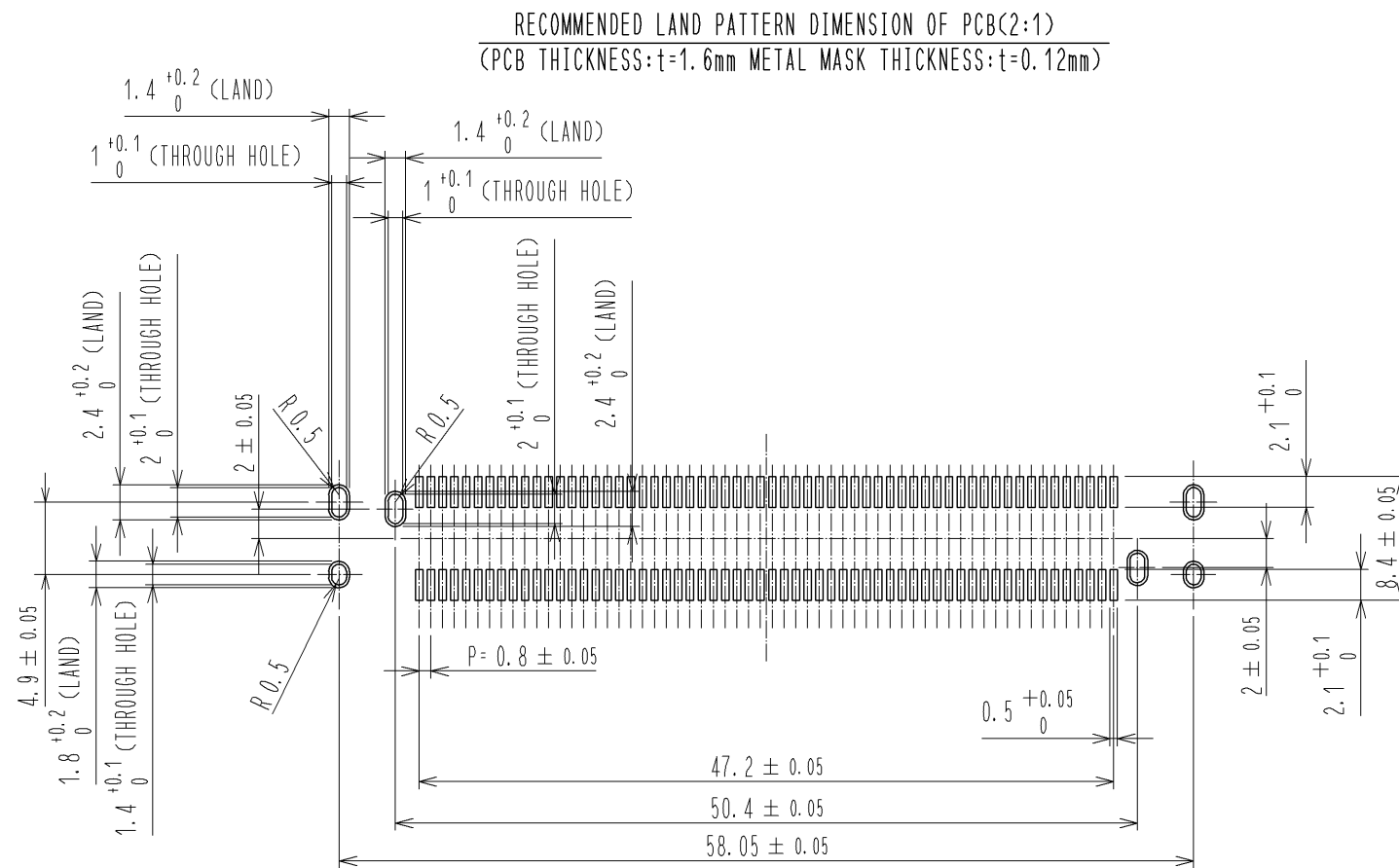


CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=20mm



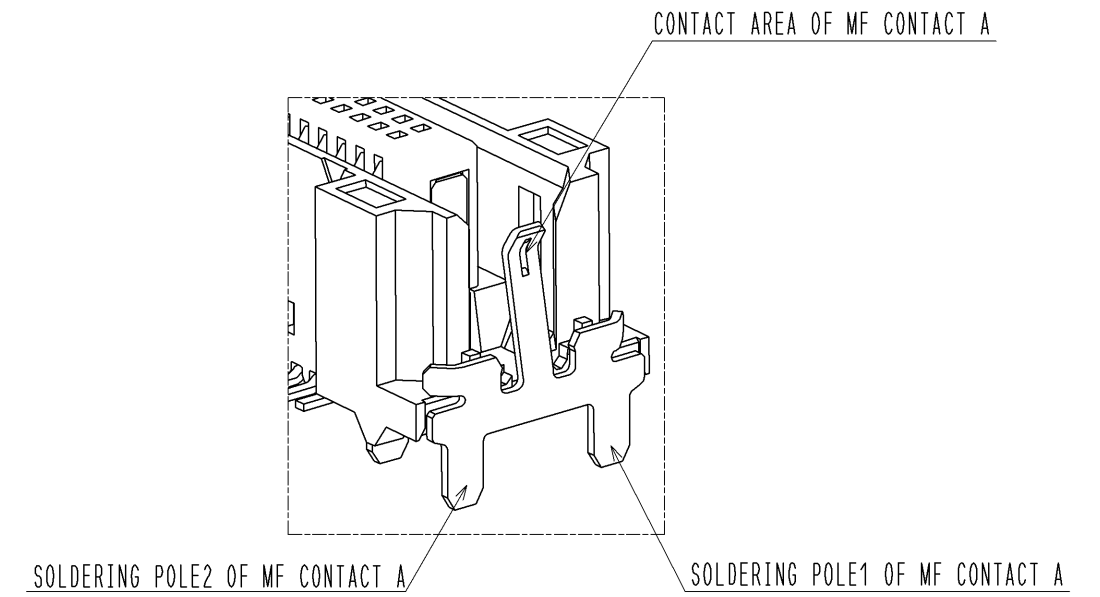
			6	POLYIMIDE			
			5	POLYSTYRENE			
2	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm		
		LEAD AREA:GOLD 0.03 μm			LEAD AREA:TIN-PLATING 1 μm		
		UNDER PLATING:NICKEL 1.3 μm			UNDER PLATING:NICKEL 1.3 μm		
1	POLYAMIDE	BLACK UL94V-0	3	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm		
					LEAD AREA:TIN-PLATING 1 μm		
					UNDER PLATING:NICKEL 1.3 μm		
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS	

UNITS mm		SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
 HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA	14. 07. 16	DRAWING NO.	EDC3-349391-00			
		CHECKED : HT. YAMAGUCHI	14. 07. 15	PART NO.	FX18-120S-0. 8SV10			
		DESIGNED : TH. SANO	14. 07. 15	CODE NO.	CL579-0059-2-00			
		DRAWN : TH. SANO	14. 07. 15					1/2

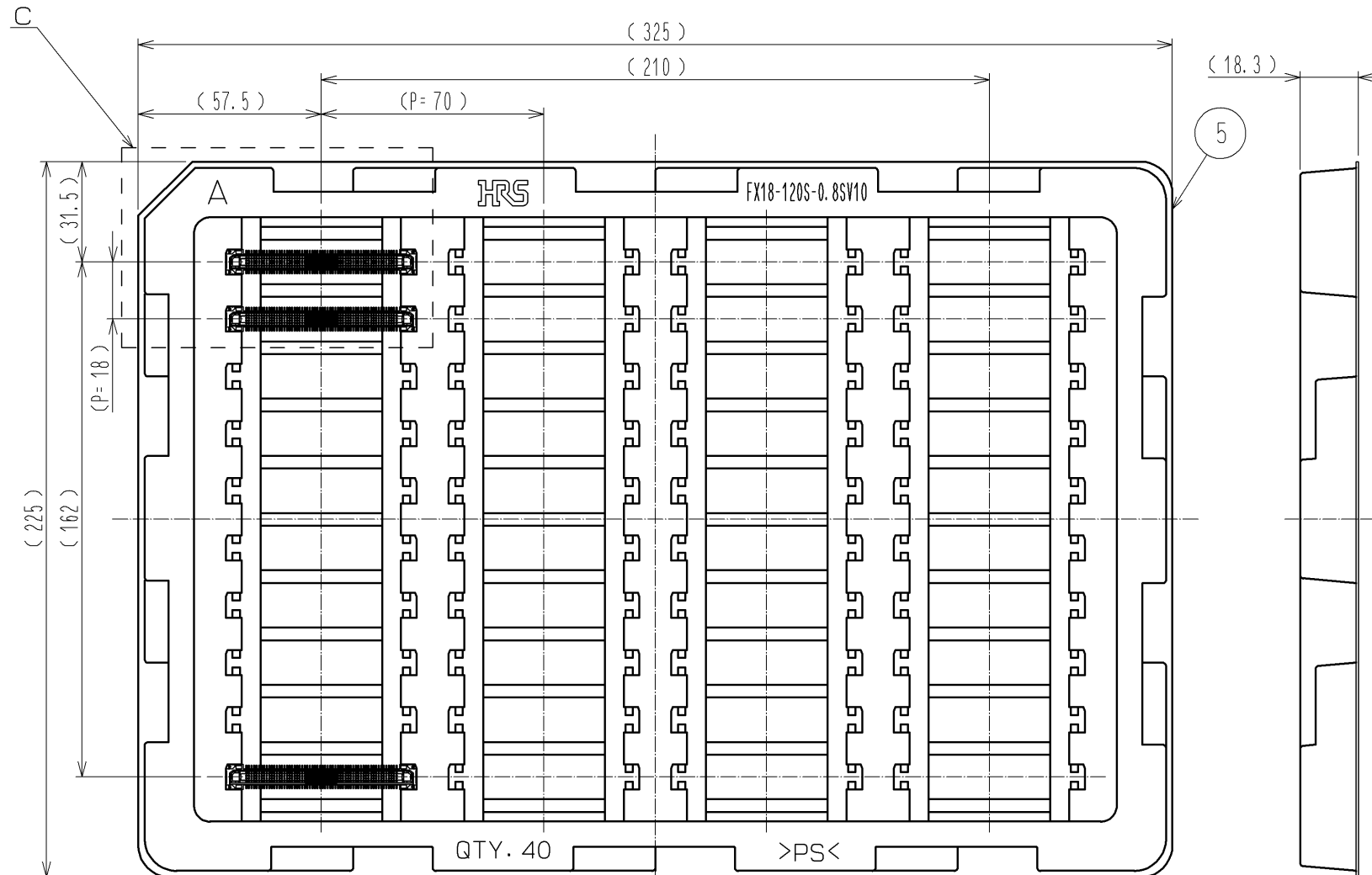


5 DRAWING FOR PACKING(1:2)

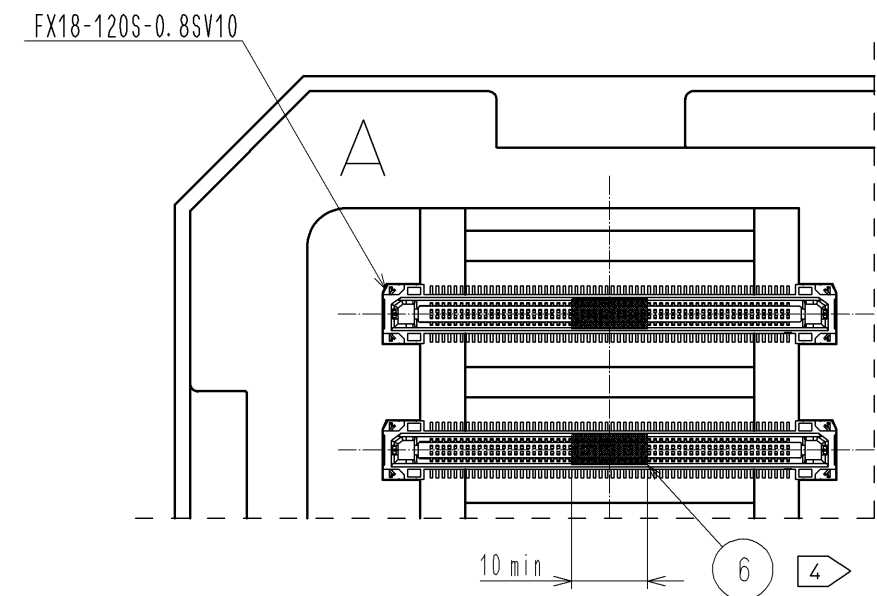
8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.



C(1:1)



HRS

DRAWING NO.	EDC3-349391-00
PART NO.	FX18-120S-0.8SV10
CODE NO.	CL579-0059-2-00

2/2